# PME261 Series Metallized Impregnated Paper, 10.2 – 25.4 mm Lead Spacing, 400 – 1,000 VDC



### Overview

The PME261 Series is constructed of multilayer metallized paper, encapsulated and impregnated in self-extinguishing material meeting the requirements of UL 94 V-0.

### **Benefits**

- Voltage range: 400 1,000 VDC; 220 500 VAC
- Capacitance range: 0.001 1 μF
- Lead spacing: 10.2 25.4 mm
- Capacitance tolerance: ±10%, ±20%, ±5% on request
- Climatic category: 40/70/56, IEC 60068-1
- Tape and reel packaging in accordance with IEC 60286-2
- · RoHS Compliant and lead-free terminations
- Operating temperature range of -40°C to +70°C in AC applications



For general use in DC and low frequency pulse applications.

**Applications** 

# Legacy Part Number System

PME261	К	Α	5100	К	R30
Series	Rated Voltage (VAC)	Lead Spacing (mm)	Capacitance Code (pF)	Capacitance Tolerance	Packaging
Metallized Paper	K = 220 E = 300 J = 500	A = 10.2 B = 15.2 C = 20.3 E = 25.4	The last three digits represent significant figures. First digit specifies the total number of digits in the capacitance value.	J = ±5% K = ±10% M = ±20%	See Ordering Options Table

# **New KEMET Part Number System**

Р	561	Н	E	103	K	220	Α
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Packaging
P = Paper	Metallized Paper General Purpose	H = 10.2 Q = 15.2 C = 20.3 E = 25.4	See Dimension Table	First two digits indicate the two most significant digits of the capacitance value in picofarads. The third digit is the number of following zeroes.	J = ±5% K = ±10% M = ±20%	220 = 220 300 = 300 500 = 500	See Ordering Options Table

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# **Benefits cont'd**

- Operating temperature range of -40°C to +100°C in DC applications
- Excellent self-healing properties. Ensures long life even when subjected to frequent over-voltages.
- · Good resistance to ionization due to impregnated dielectric
- IEC Publication 166 Type 1
- High dV/dt capability

- Approved according to SE-MIL-QPL
- The capacitors meet the most stringent IEC humidity class, 56 days
- The impregnated paper ensures excellent stability giving outstanding reliability properties, especially in applications having continuous operation

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
	Bulk (Bag) – Max Length Leads	17 +0/-1	A	R17
10.2	Tape & Reel (Standard Reel)	H <sub>0</sub> = 18.5 +/-0.5	L	R19T0
	Other Lead and Packaging Options			
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 +/-0.5	Р	R19T1
Native 10.2 formed to 7.5	Ammo Pack	H <sub>0</sub> = 16.5 +/-0.5	LAF3	R30XA
	Standard Lead and Packaging			
	Options	6.0/1	0	DOC
	Bulk (Bag) – Short Leads	6 +0/-1	C	R06
15.2	Bulk (Bag) – Max Length Leads	30 +5/-0 H <sub>o</sub> = 18.5	A	R30
13.2	Tape & Reel (Standard Reel)	+/-0.5	L	R19T0
	Other Lead and Packaging Options			
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 +/-0.5	Р	R19T1
	Standard Lead and Packaging			
	Options			
	Bulk (Tray) – Short Leads	6 +0/-1	С	R06
	Bulk (Bag) – Max Length Leads	30 +5/-0	A	R30
20.3	Tape & Reel (Standard Reel)	H <sub>o</sub> = 18.5 +/-0.5	L	R19T0
	Other Lead and Packaging Options			
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 +/-0.5	Р	R19T1

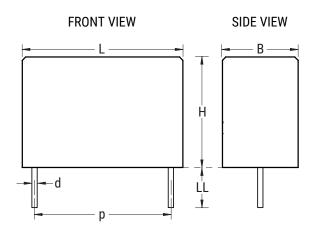
# **Ordering Options Table**



# **Ordering Options Table cont'd**

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
25.4	Bulk (Tray) – Short Leads	6 +0/-1	С	R06
	Bulk (Bag) – Max Length Leads	30 +5/-0	А	R30

# **Dimensions – Millimeters**



Size Code		р	l	B		н		L		d
Size Code	Nominal Tolerance		Nominal Tolerance		Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
HE	10.2	+/-0.4	3.9	Maximum	7.5	Maximum	13.5	Maximum	0.6	+/-0.05
HL	10.2	+/-0.4	5.1	Maximum	10.5	Maximum	13.5	Maximum	0.6	+/-0.05
QE	15.2	+/-0.4	5.2	Maximum	10.5	Maximum	18.5	Maximum	0.8	+/-0.05
QM	15.2	+/-0.4	7.3	Maximum	13.0	Maximum	18.5	Maximum	0.8	+/-0.05
QP	15.2	+/-0.4	7.8	Maximum	13.5	Maximum	18.5	Maximum	0.8	+/-0.05
CE	20.3	+/-0.4	7.6	Maximum	14.0	Maximum	24.0	Maximum	0.8	+/-0.05
CG	20.3	+/-0.4	8.4	Maximum	14.0	Maximum	24.0	Maximum	0.8	+/-0.05
CJ	20.3	+/-0.4	9.0	Maximum	15.0	Maximum	24.0	Maximum	0.8	+/-0.05
CP	20.3	+/-0.4	11.3	Maximum	16.5	Maximum	24.0	Maximum	0.8	+/-0.05
EH	25.4	+/-0.4	10.6	Maximum	17.3	Maximum	30.5	Maximum	1	+/-0.05
EL	25.4	+/-0.4	15.3	Maximum	22.0	Maximum	30.5	Maximum	1	+/-0.05
			Note: See	e Ordering Optic	ons Table for l	ead length (LL)	options.			



# **Performance Characteristics**

Rated Voltage V <sub>R</sub> (VDC)	400	630	1000			
Rated Voltage $V_{R}$ (VAC)	220	500				
Capacitance Range (µF)	0.0082 - 1.0 0.001 - 0.15 0.001 - 0.1					
Capacitance Tolerance	±10%, ±20%, ±5% on re	equest				
Townseture Dance	-40 to +70°C					
Temperature Range	-40 to +100°C					
Climatic Category	40/070/56					
Dissingtion Foster ton S	Maximum Values at +23°C					
Dissipation Factor tanδ	1 k	Hz	1.3%			
	Measured a	at +20°C, According to IE	C 60384-2			
	Minimum Values Between Terminals					
Insulation Resistance	C ≤ 0.	33 µF	≥ 12,000 MΩ			
Insulation Resistance	C > 0.33 μF ≥ 4,000 MΩ • μF					
	PME261 K measured at 100 VDC after 60 seconds, +23°C					
	PME261 E and J measured at 500 VDC after 60 seconds, +23°C					

# **Environmental Test Data**

Test	IEC Publication	Procedure
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10 – 55 Hz at 0.75 mm or 98 m/s <sup>2</sup>
Bump	IEC 60068-2-29 Test Eb	4,000 bumps at 390 m/s <sup>2</sup>
Solderability	IEC 60068-2-20 Test Ta	Solder globule method Wetting time for d ≤ 0.8 < 1 second for d > 0.8 < 1.5 seconds
Passive Flammability	IEC 60695-2-2	
Damp Heat Steady State	IEC 60068-2-3 Test Ca	+40°C and 90 – 95% RH, 56 days

# **Environmental Compliance**

All KEMET Metallized Impregnated Paper capacitors are RoHS Compliant.



### Table 1 – Ratings & Part Number Reference

Capacitance		Maximun ensions ii		Lead	dV/dt	New Kemet	Legacy Part Number
Value (µF)	В	н	L L	Spacing (p)	(V/µs)	Part Number	Part Number
0.0082	3.9	7.5	13.5	10.2	2000	P561HE822(1)220(2)	PME261KA4820(1)(2)
0.010	3.9	7.5	13.5	10.2	2000	P561HE103(1)220(2)	PME261KA5100(1)(2)
0.015	5.1	10.5	13.5	10.2	2000	P561HL153(1)220(2)	PME261KA5150(1)(2)
0.022	5.1	10.5	13.5	10.2	2000	P561HL223(1)220(2)	PME261KA5220(1)(2)
0.033	5.2	10.5	18.5	15.2	1600	P561QE333(1)220(2)	PME261KB5330(1)(2)
0.047	5.2	10.5	18.5	15.2	1300	P561QE473(1)220(2)	PME261KB5470(1)(2)
0.068	7.3	13.0	18.5	15.2	1100	P561QM683(1)220(2)	PME261KB5680(1)(2)
0.1	7.3	13.0	18.5	15.2	850	P561QM104(1)220(2)	PME261KB6100(1)(2)
0.15	7.6	14.0	24.0	20.3	700	P561CE154(1)220(2)	PME261KC6150(1)(2)
0.22	8.4	14.0	24.0	20.3	560	P561CG224(1)220(2)	PME261KC6220(1)(2)
0.33	11.3	16.5	24.0	20.3	430	P561CP334(1)220(2)	PME261KC6330(1)(2)
0.47	10.6	17.3	30.5	25.4	370	P561EH474(1)220(2)	PME261KE6470(1)(2)
0.68	15.3	22.0	30.5	25.4	300	P561EL684(1)220(2)	PME261KE6680(1)(2)
1	15.3	22.0	30.5	25.4	220	P561EL105(1)220(2)	PME261KE7100(1)(2)
0.001	3.9	7.5	13.5	10.2	2000	P561HE102(1)300(2)	PME261EA4100(1)(2)
0.0015	3.9	7.5	13.5	10.2	2000	P561HE152(1)300(2)	PME261EA4150(1)(2)
0.0022	3.9	7.5	13.5	10.2	2000	P561HE222(1)300(2)	PME261EA4220(1)(2)
0.0033	3.9	7.5	13.5	10.2	2000	P561HE332(1)300(2)	PME261EA4330(1)(2)
0.0047	3.9	7.5	13.5	10.2	2000	P561HE472(1)300(2)	PME261EA4470(1)(2)
0.0068	3.9	7.5	13.5	10.2	2000	P561HE682(1)300(2)	PME261EA4680(1)(2)
0.01	5.1	10.5	13.5	10.2	2000	P561HL103(1)300(2)	PME261EA5100(1)(2)
0.015	5.1	10.5	13.5	10.2	2000	P561HL153(1)300(2)	PME261EA5150(1)(2)
0.022	5.2	10.5	18.5	15.2	2000	P561QE223(1)300(2)	PME261EB5220(1)(2)
0.033	5.2	10.5	18.5	15.2	2000	P561QE333(1)300(2)	PME261EB5330(1)(2)
0.047	7.3	13.0	18.5	15.2	1600	P561QM473(1)300(2)	PME261EB5470(1)(2)
0.068	7.3	13.0	18.5	15.2	1200	P561QM683(1)300(2)	PME261EB5680(1)(2)
0.1	7.6	14.0	24.0	20.3	900	P561CE104(1)300(2)	PME261EC6100(1)(2)
0.15	9.0	15.0	24.0	20.3	650	P561CJ154(1)300(2)	PME261EC6150(1)(2)
0.001	3.9	7.5	13.5	10.2	2000	P561HE102(1)500(2)	PME261JA4100(1)(2)
0.0015	3.9	7.5	13.5	10.2	2000	P561HE152(1)500(2)	PME261JA4150(1)(2)
0.0022	3.9	7.5	13.5	10.2	2000	P561HE222(1)500(2)	PME261JA4220(1)(2)
0.0033	3.9	7.5	13.5	10.2	2000	P561HE332(1)500(2)	PME261JA4330(1)(2)
0.0047	5.1	10.5	13.5	10.2	2000	P561HL472(1)500(2)	PME261JA4470(1)(2)
0.0068	5.1	10.5	13.5	10.2	2000	P561HL682(1)500(2)	PME261JA4680(1)(2)
0.01	5.2	10.5	18.5	15.2	2000	P561QE103(1)500(2)	PME261JB5100(1)(2)
0.015	5.2	10.5	18.5	15.2	2000	P561QE153(1)500(2)	PME261JB5150(1)(2)
0.022	7.3	13.0	18.5	15.2	2000	P561QM223(1)500(2)	PME261JB5220(1)(2)
0.033	7.8	13.5	18.5	15.2	2000	P561QP333(1)500(2)	PME261JB5330(1)(2)
0.047	7.6	14.0	24.0	20.3	2000	P561CE473(1)500(2)	PME261JC5470(1)(2)
0.068	9.0	15.0	24.0	20.3	1400	P561CJ683(1)500(2)	PME261JC5680(1)(2)
0.1	11.3	16.5	24.0	20.3	950	P561CP104(1)500(2)	PME261JC6100(1)(2)
Capacitance Value (µF)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	dV/dt (V/µs)	New KEMET Part Number	Legacy Part Number

(1)  $K = \pm 10\%$ ,  $M = \pm 20\%$ ,  $J = \pm 5\%$  on request.

(2) Insert lead and packaging code. See Ordering Options Table for available options.



# **Soldering Process**

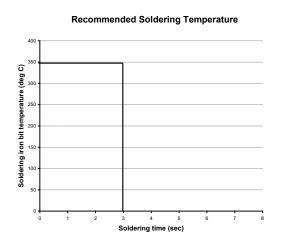
The implementation of the RoHS directive has resulted in the selection of SnAgCu (SAC) alloys or SnCu alloys as primary solder. This has increased the liquidus temperature from that of 183°C for SnPb eutectic alloy to 217 – 221°C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is 160 – 170°C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 mm to 15 mm), and great care has to be taken during soldering. The recommended solder profiles from KEMET should be used. Please consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. Please see Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the above the recommended limits may result to degradation or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface mount components. Insert through-hole parts after the curing of surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum two soldering cycles is recommended. Please allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

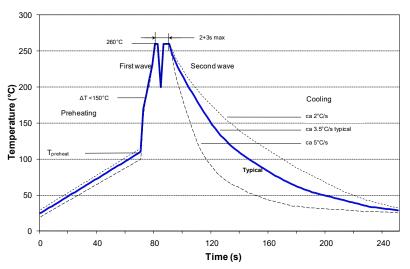
#### Manual Soldering Recommendations

Following is the recommendation for manual soldering with a soldering iron.



The soldering iron tip temperature should be set at 350°C (+10°C maximum) with the soldering duration not to exceed more than 3 seconds.

#### **Wave Soldering Recommendations**





# Soldering Process cont'd

#### Wave Soldering Recommendations cont'd

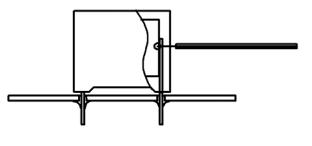
1. The table indicates the maximum set-up temperature of the soldering process Figure 1

Dielectric		imum Pre emperatu	Maximum Peak Soldering Temperature			
Film Material	Capacitor Pitch ≤ 10 mm	Capacitor Pitch = 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	130°C	270°C	270°C	
Polypropylene	100°C	110°C	130°C	260°C	270°C	
Paper	130°C	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor:

Set the temperature so that inside the element the maximum temperature is below the limit:

Dielectric Film Material	Maximum temperature measured inside the element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene sulphide	160°C



Temperature monitored inside the capacitor.

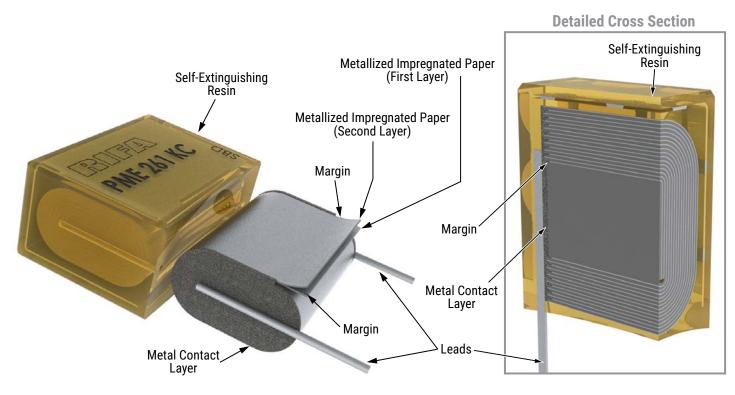
#### **Selective Soldering Recommendations**

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath as in normal flow soldering without touching the solder. When the board is over the bath, it is stopped and pre-designed solder pots are lifted from the bath with molten solder only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

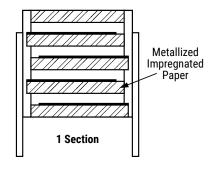
The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document, **however, instead of two baths, there is only one bath with a time from 3 to 10 seconds.** In selective soldering, the risk of overheating is greater than in double wave flow soldering, and great care must be taken so that the parts are not overheated.



### Construction

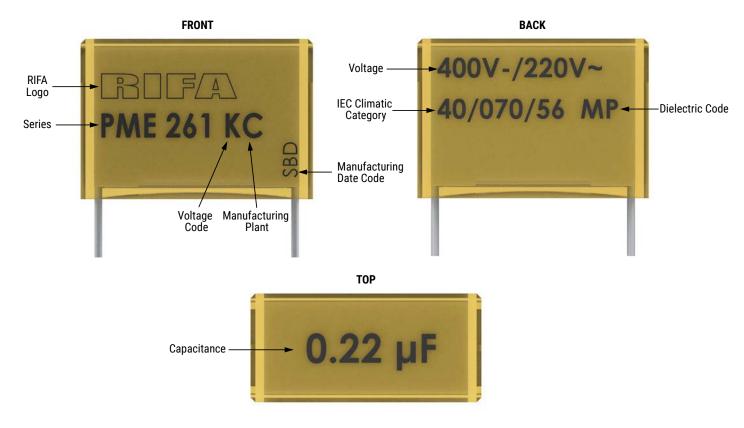


Winding Scheme





# Marking





# **Packaging Quantities**

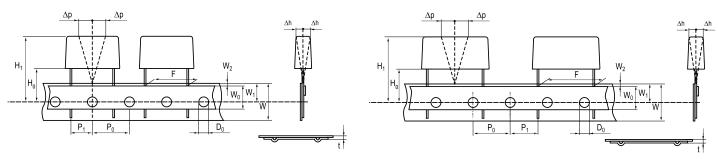
Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel ø 360 mm	Large Reel ø 500 mm	Ammo Formed
	3.9	7.5	13.5	2000	1000	700	1400	800
10.2	4.1	8.2	13.5	2000	1000	600		780
	5.1	10.5	13.5	1600	800	600	1200	630
				r	1			
	5.5	12.5	18	1000	500	600		
	6.5	12.5	18	600	400	400		
	7.5	14.5	18	600	400	400		
	8.5	16	18	400	250	400		
15.2	5.2	10.5	18.5	1000	500	600		
15.2	5.5	11	18.5	1000	500	500		
	6	12.5	18.5	600	400	400		
	7.3	13	18.5	600	400	400	800	
	7.8	13.5	18.5	600	400	400		
	8.5	14.3	18.5	500	300	350		
	7.6	14	24	1500	250	250	500	
	8.4	14	24	1200	200	250	500	
20.3	9	15	24	1500	200	250		
	11.3	16.5	24	1000	150	180	400	
				·	~ 		· · · · · · · · · · · · · · · · · · ·	
	10.6	16.1	30.5	1000	150			
25.4	10.5	17.3	30.5	1000	100			
23.7	12.1	19	30.5	800	100			
	15.3	22	30.5	600	75			



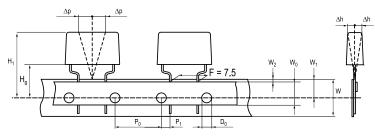
# Lead Taping & Packaging (IEC 60286-2)

#### Lead Spacing 10.2 - 15.2 mm

Lead Spacing 20.3 – 22.5 mm



#### Formed Leads from 10.2 to 7.5 mm



# **Taping Specification**

	Dimensions in mm										
Lead spacing	+6/-0.1	F	Formed 7.5	10.2	15.2	20.3	22.5	F			
Carrier tape width	+/-0.5	W	18	18	18	18	18	18+1/-0.5			
Hold-down tape width	+/-0.3	W <sub>o</sub>	9	12	12	12	12				
Position of sprocket hole	+/-0.5	<b>W</b> <sub>1</sub>	9	9	9	9	9	9+0.75/-0.5			
Distance between tapes	Maximum	W <sub>2</sub>	3	3	3	3	3	3			
Sprocket hole diameter	+/-0.2	D <sub>0</sub>	4	4	4	4	4	4			
Feed hole lead spacing	+/-0.3	P <sub>0</sub> <sup>(1)</sup>	12.7(4)	12.7	12.7	12.7	12.7	12.7			
Distance lead – feed hole	+/-0.7	P <sub>1</sub>	3.75	7.6	5.1	8.9	5.3	P <sup>1</sup>			
Deviation tape – plane	Maximum	Δp	1.3	1.3	1.3	1.3	1.3	1.3			
Lateral deviation	Maximum	Δh	2	2	2	2	2	2			
Total thickness	+/-0.2	t	0.7	0.7	0.7	0.7	0.9 <sup>max</sup>	0.9 <sup>max</sup>			
Sprocket hole/cap body	Nominal	H <sub>0</sub> <sup>(2)</sup>	18+2/-0	18+2/-0	18+2/-0	18+2/-0	18.5+/-0.5	18+2/-0			
Sprocket hole/top of cap body	Maximum	H <sub>1</sub> <sup>(3)</sup>	35	35	35	35	58	58 <sup>max</sup>			

(1) Maximum cumulative feed hole error, 1 mm per 20 parts.(2) 16.5 mm available on request.

(3) Depending on case size.(4) 15 mm available on request.



# Lead Taping & Packaging (IEC 60286-2) cont'd

# **Ammo Specifications**

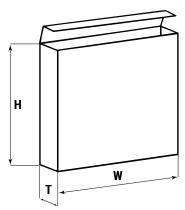
Series	Dimensions (mm)		
Series	Н	W	Т
R4x, R4x+R, R7x, RSB			
F5A, F5B, F5D	360	340	59
F6xx, F8xx			
PHExxx, PMExxx, PMRxxx	330	330	50

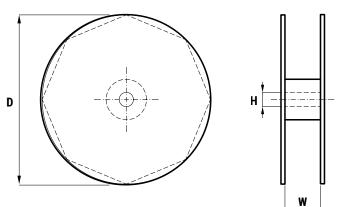
# **Reel Specifications**

Series	Dimensions (mm)		
Series	D	Н	W
R4x, R4x+R, R7x, RSB			
F5A, F5B, F5D	355 500	30 25	55 (Max)
F6xx, F8xx	500	25	
PHExxx, PMExxx, PMRxxx	360 500	30	46 (Max)

# Manufacturing Date Code (IEC-60062)

Y = Year, Z = Month					
Year	Code	Month	Code		
2000	М	January	1		
2001	N	February	2		
2002	Р	March	3		
2003	R	April	4		
2004	S	May	5		
2005	Т	June	6		
2006	U	July	7		
2007	V	August	8		
2008	W	September	9		
2009	Х	October	0		
2010	A	November	Ν		
2011	В	December	D		
2012	С				
2013	D				
2014	E				
2015	F				
2016	Н				
2017	J				
2018	K				
2019	L				
2020	М				







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